



16-Bit, 10 MSPS ANALOG-TO-DIGITAL CONVERTER

FEATURES

- High-Speed, Wide Bandwidth $\Delta\Sigma$ ADC
- 10MSPS Output Data Rate
- 4.9MHz Signal Bandwidth
- 86dBFS Signal-to-Noise Ratio
- –94dB Total Harmonic Distortion
- 95dB Spurious-Free Dynamic Range
- On-Chip Digital Filter Simplifies Anti-Alias Requirements
- SYNC Pin for Simultaneous Sampling with Multiple ADS1610s
- Low 3μs Group Delay
- Parallel Interface
- Directly Connects to TMS320 DSPs
- Out-of-Range Alert Pin

APPLICATIONS

- Scientific Instruments
- Test Equipment
- Communications

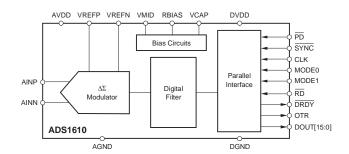
DESCRIPTION

The ADS1610 is a high-speed, high-precision, delta-sigma $(\Delta\Sigma)$ analog-to-digital converter (ADC) with 16-bit resolution operating from a 5V analog and a 3V digital supply. Featuring an advanced multi-stage analog modulator combined with an on-chip digital decimation filter, the ADS1610 achieves 86 dBFS signal-to-noise ratio (SNR) in a 5MHz signal bandwidth; while the total harmonic distortion is -94dB.

The ADS1610 $\Delta\Sigma$ topology provides key system-level design advantages with respect to anti-alias filtering and clock jitter. The design of the user's front-end anti-alias filter is simplified since the on-chip digital filter greatly attenuates out-of-band signals. The ADS1610s filter has a *brick wall* response with a very flat passband (± 0.0002 dB of ripple) followed immediately by a very wide stop band (± 0.0002 dB of ripple) followed immediately by a very wide stop band (± 0.0002 dB of ripple) followed immediately by a very wide stop band (± 0.0002 dB of ripple) followed immediately by a very wide stop band (± 0.0002 dB of ripple) followed immediately by a very wide stop band (± 0.0002 dB of ripple) followed immediately by a very wide stop band (± 0.0002 dB of ripple) followed immediately by a very wide stop band (± 0.0002 dB of ripple) followed immediately by a very wide stop band (± 0.0002 dB of ripple) followed immediately by a very wide stop band (± 0.0002 dB of ripple) followed immediately by a very wide stop band (± 0.0002 dB of ripple) followed immediately by a very wide stop band (± 0.0002 dB of ripple) followed immediately by a very wide stop band (± 0.0002 dB of ripple) followed immediately by a very wide stop band (± 0.0002 dB of ripple) followed immediately by a very wide stop band (± 0.0002 dB of ripple) followed immediately by a very wide stop band (± 0.0002 dB of ripple) followed immediately by a very wide stop band (± 0.0002 dB of ripple) followed immediately by a very wide stop band (± 0.0002 dB of ripple) followed immediately by a very wide stop band (± 0.0002 dB of ripple) followed immediately by a very wide stop band (± 0.0002 dB of ripple) followed immediately by a very wide stop band (± 0.0002 dB of ripple) followed immediately by a very wide stop band (± 0.0002 dB of ripple) followed immediately by a very wide stop band (± 0.0002 dB of ripple) followed immediately by a very wide stop band (± 0.0002 dB of ripple) followed immediately by a very wide stop band (

Output data is supplied over a parallel interface and easily connects to TMS320 digital signal processors (DSPs). The power dissipation can be adjusted with an external resistor, allowing for reduction at lower operating speeds.

With its outstanding high-speed performance, the ADS1610 is well-suited for demanding applications in data acquisition, scientific instruments, test and measurement equipment, and communications. The ADS1610 is offered in a TQFP64 package and is specified from -40°C to 85°C.





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ADS1610 passes 1.5K CDM testing. ADS1610 passes 1kV human body model testing (TI Standard is 2kV).

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION

For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted) (1)

| | VALUE | UNIT |
|--|--------------------|-------|
| AVDD to AGND | -0.3 to +6 | V |
| DVDD to DGND | -0.3 to +3.6 | V |
| AGND to DGND | -0.3 to +0.3 | V |
| lanut current I | 100, Momentary | A |
| Input current, I _I | 10, Continuous | mA mA |
| Analog I/O to AGND | -0.3 to AVDD + 0.3 | V |
| Digital I/O to DGND | -0.3 to DVDD + 0.3 | V |
| Maximum junction temperature, T _J | 150 | °C |
| Operating free-air temperature range, T _A | -40 to +105 | °C |
| Storage temperature range, T _{stg} | -60 to +150 | °C |
| Lead temperature (soldering, 10s) | 260 | °C |

⁽¹⁾ Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

ELECTRICAL CHARACTERISTICS

All specifications at -40° C to 85°C, AVDD = 5V, DVDD = 3V, f_{CLK} = 60MHz, V_{REF} = 3V, MODE = 00, V_{CM} = 2.5V, and RBIAS = 19k Ω (unless otherwise noted).

| | PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--------------------------------|--|----------------------------------|------|---|-----|------|
| ANALOG INPUT | | | | | | |
| V _{ID(AINP - AINN)} | Differential input voltage (AINP-AINN) | | | ±V _{REF} | | V |
| V _{IC(AINP + AINN)/2} | Common-mode input voltage | | | 2.5 | | V |
| V _{IHA} | Absolute input voltage (AINP or AINN with respect to AGND) | | -0.1 | | 4.2 | V |
| DYNAMIC SPECI | FICATIONS | | | | | |
| | Data rate | | | $10\left(\frac{f_{CLK}}{60 \text{ MHz}}\right)$ | | MSPS |
| SNR | Signal-to-noise ration relative to full-scale ⁽¹⁾ | f _{IN} = 100kHz, -2dBFS | 83 | 86 | | dBFS |

⁽¹⁾ For reference, this dynamic specification is extrapolated to full-scale and is thus dBFS. Subsequent dynamic specifications are dBc (dB), which is: Specification (in dBc) = Specification (in dBFS) + AIN (input amplitude in dBFS). For more information see Understanding and comparing datasheets for high-speed ADCs.



ELECTRICAL CHARACTERISTICS (continued)

All specifications at -40° C to 85°C, AVDD = 5V, DVDD = 3V, f_{CLK} = 60MHz, V_{REF} = 3V, MODE = 00, V_{CM} = 2.5V, and RBIAS = 19k Ω (unless otherwise noted).

| | PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|-------|--------------------------------|-----------------------------------|------|-------------|------|---------|
| | | f _{IN} = 100kHz, -2dBFS | 81 | 84 | | |
| | | f _{IN} = 100kHz, -6dBFS | 77 | 80 | | |
| | | f _{IN} = 100kHz, -20dBFS | | 66 | | |
| | | f _{IN} = 1MHz, -2dBFS | | 83 | | |
| SNR | Signal-to-noise ratio | f _{IN} = 1MHz, -6dBFS | | 80 | | dB |
| | | f _{IN} = 1MHz, -20dBFS | | 66 | | |
| | | f _{IN} = 4MHz, -2dBFS | 79.5 | 83 | | |
| | | f _{IN} = 4MHz, -6dBFS | 76 | 79 | | |
| | | f _{IN} = 4MHz, -20dBFS | | 65 | | |
| | | f _{IN} = 100kHz, -2dBFS | | -90 | -83 | |
| | | f _{IN} = 100kHz, -6dBFS | | -95 | -85 | |
| | | f _{IN} = 100kHz, -20dBFS | | -95 | | |
| | | f _{IN} = 1MHz, -2dBFS | | - 91 | | |
| THD | Total harmonic distortion | f _{IN} = 1MHz, -6dBFS | | -93 | | dB |
| | | f _{IN} = 1MHz, -20dBFS | | -95 | | |
| | | f _{IN} = 4MHz, -2dBFS | | -109 | -100 | |
| | | f _{IN} = 4MHz, -6dBFS | | -105 | -100 | |
| | | f _{IN} = 4MHz, -20dBFS | | -95 | | |
| | | f _{IN} = 100kHz, -2dBFS | | 83 | | |
| | | f _{IN} = 100kHz, -6dBFS | | 79 | | |
| | | f _{IN} = 100kHz, -20dBFS | | 65 | | |
| | | f _{IN} = 1MHz, –2dBFS | | 82 | | |
| SINAD | Signal-to-noise and distortion | f _{IN} = 1MHz, -6dBFS | | 79 | | dB |
| | | f _{IN} = 1MHz, -20dBFS | | 65 | | |
| | | f _{IN} = 4MHz, –2dBFS | | 83 | | |
| | | f _{IN} = 4MHz, -6dBFS | | 79 | | |
| | | f _{IN} = 4MHz, -20dBFS | | 65 | | |
| | | f _{IN} = 100kHz, -2dBFS | 85 | 90 | | |
| | | f _{IN} = 100kHz, -6dBFS | 90 | 96 | | |
| | | f _{IN} = 100kHz, -20dBFS | | 96 | | |
| | | f _{IN} = 1MHz, -2dBFS | | 94 | | |
| SFDR | Spurious-free dynamic range | f _{IN} = 1MHz, -6dBFS | | 94 | | dB |
| | | f _{IN} = 1MHz, -20 dBFS | | 96 | | |
| | | f _{IN} = 4MHz, –2dBFS | 100 | 109 | | 1 |
| | | f _{IN} = 4MHz, -6dBFS | 100 | 105 | | 1 |
| | | f _{IN} = 4MHz, –20dBFS | | 95 | | |
| | Aperture jitter | Excludes jitter of CLK source | | 2 | | ps, rms |
| | Aperture delay | | | 4 | | ns |



ELECTRICAL CHARACTERISTICS (Continued)

All specifications at -40° C to 85°C, AVDD = 5V, DVDD = 3V, f_{CLK} = 60MHz, V_{REF} = 3V, MODE = 00, V_{CM} = 2.5V, and RBIAS = 19k Ω (unless otherwise noted).

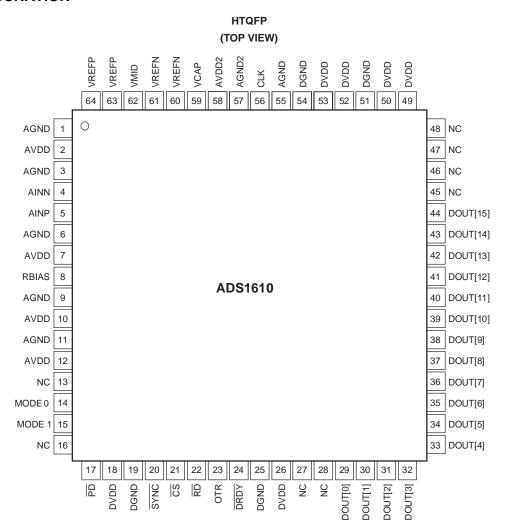
| STATIC SPECIFICATIONS | | PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|---|-------------------|------------------------------------|--|---------|---|--|-----------|
| Passband ripple | DIGITAL | FILTER CHARACTERISTICS | ' | | | 1 | |
| Passband ripple | | | | | | / four \ | |
| Passband transition | | Passband | | 0 | | $4.4\left(\frac{^{1}CLK}{60 \text{ MHz}}\right)$ | MHz |
| Passband transition | | Passband ripple | | | | ±0.0002 | dB |
| Stop band S.6 See Figure 3 S4.4 MHz | | Passband transition | -0.1dB attenuation | | $4.6 \left(\frac{f_{CLK}}{60 \text{ MHz}} \right)$ | | MHz |
| Stop band attentuation 80 See Figure 34 dB | | | -3.0dB attenuation | | $4.9 \left(\frac{f_{CLK}}{60 \text{ MHz}} \right)$ | | |
| Settling time To ±0.001% S.S (60 MHz ΓCLK) | | Stop band | | 5.6 | | 54.4 | MHz |
| Settling time To ±0.001% S.S. GO MHz FCLK | | Stop band attentuation | | 80 | See Figure 34 | | dB |
| STATIC SPECIFICATIONS Resolution No missing codes 16 Bits Input mrs noise Shorted input 1.0 1.4 LSB (mrs) LSB (mrs) | $t_{d(grp)}$ | Group delay | | | $3.0 \left(\frac{60 \text{ MHz}}{\text{f}_{\text{CLK}}} \right)$ | | μs |
| Resolution No missing codes 16 | ts | Settling time | To ±0.001% | | $5.5 \left(\frac{60 \text{ MHz}}{\text{f}_{\text{CLK}}} \right)$ | | μs |
| Input ms noise | STATIC S | SPECIFICATIONS | | | | | |
| Integral nonlinearity | | Resolution | No missing codes | 16 | | | Bits |
| Integral nonlinearity | | Input rms noise | Shorted input | | 1.0 | 1.4 | LSB (rms) |
| 2.5V input | | Integral poplinearity | 1V input | | ±0.4 | | LSB |
| V _{IO} Offset error T = 25°C 0.05 %FS Offset drift 5 ppm/°C G _(ERR) Gain error T = 25°C ±0.3(¹¹) %FS G Gain drift Excluding reference drift 10 ppm/°C CMRR Common-mode rejection ratio At DC 60 dB PSRR Supply-voltage rejection ratio At DC 80 dB VOLTAGE REFERENCE V _{ref} Reference voltage, (VREFP - VREFN) 2.9 3.0 3.1 V VREFP 3.6 4.0 4.4 V VREFP No.0 0.7DVDD DVDD V </td <td></td> <td>integral nonlineality</td> <td>2.5V input</td> <td></td> <td>±1.5</td> <td></td> <td>LSB</td> | | integral nonlineality | 2.5V input | | ±1.5 | | LSB |
| Offset drift | | Differential nonlinearity | | | ±0.5 | | LSB |
| G _(ERR) Gain error T = 25°C ±0.3(1) 9%FS G Gain drift Excluding reference drift 10 ppm/°C CMRR Common-mode rejection ratio At DC 60 dB PSRR Supply-voltage rejection ratio At DC 80 dB VOLTAGE REFERENCE Voltage Reference voltage, (VREFP - VREFN) 2.9 3.0 3.1 V VREFP 3.6 4.0 4.4 V VREFN 0.9 1.0 1.1 V VMID 2.2 2.5 3.8 V DIGITAL INPUT/OUTPUT VI _{IL} High-level input voltage 0.7DVDD DVDD V VI _{IL} Low-level input voltage IOH = -50µA 0.8DVDD V VO _{IL} Low-level output voltage IOH = -50µA 0.8DVDD V VO _{IL} Low-level output voltage IOH = -50µA 0.8DVDD V VO _{IL} Low-level output voltage IOH = -50µA 0.8DVDD <td< td=""><td>V_{IO}</td><td>Offset error</td><td>T = 25°C</td><td></td><td>0.05</td><td></td><td>%FS</td></td<> | V_{IO} | Offset error | T = 25°C | | 0.05 | | %FS |
| G Gain drift | | Offset drift | | | 5 | | ppm/°C |
| CMRR Common-mode rejection ratio At DC 60 dB PSRR Supply-voltage rejection ratio At DC 80 dB VOLTAGE REFERENCE Vref Reference voltage, (VREFP - VREFN) 2.9 3.0 3.1 V VREFP 3.6 4.0 4.4 V VREFN 0.9 1.0 1.1 V VMID 2.2 2.5 3.8 V DIGITAL INPUT/OUTPUT VI High-level input voltage DCADD DVDD V VI Low-level input voltage DGND 0.3DVDD V VO High-level output voltage IoL = 50μA 0.8DVDD V VO Low-level output voltage IoL = 50μA 0.2DVDD V Ikg Input leakage current DGND 0.2DVDD V Vo DVD Voltage 4.9 5.0 5.1 V VODD AVDD voltage 2.7 3.0 3.6 V | $G_{(ERR)}$ | Gain error | T = 25°C | | ±0.3 ⁽¹⁾ | | %FS |
| PSRR Supply-voltage rejection ratio At DC 80 dB VOLTAGE REFERENCE | G | Gain drift | Excluding reference drift | | 10 | | ppm/°C |
| Voltage Reference Voltage Reference voltage, (VREFP - VREFN) 2.9 3.0 3.1 V | CMRR | Common-mode rejection ratio | At DC | | 60 | | dB |
| V _{ref} Reference voltage, (VREFP - VREFN) 2.9 3.0 3.1 V VREFP 3.6 4.0 4.4 V VREFN 0.9 1.0 1.1 V VMID 2.2 2.5 3.8 V DIGITAL INPUT/OUTPUT V _I High-level input voltage 0.7DVDD DVDD V V _I Low-level input voltage DGND 0.3DVDD V V _O High-level output voltage I _{OH} = -50μA 0.8DVDD V V _O Low-level output voltage I _{OL} = 50μA 0.2DVDD V I _I Input leakage current DGND < V _{DIGITAL INPUT} < DVDD | PSRR | Supply-voltage rejection ratiio | At DC | | 80 | | dB |
| VREFP S.6 4.0 4.4 V | | E REFERENCE | - | | | | |
| VREFN 0.9 1.0 1.1 V V V V V V V V V | V_{ref} | Reference voltage, (VREFP - VREFN) | | 2.9 | 3.0 | 3.1 | V |
| VMID 2.2 2.5 3.8 V DIGITAL INPUT/OUTPUT V _{IH} High-level input voltage 0.7DVDD DVDD V V _{IL} Low-level input voltage DGND 0.3DVDD V V _{OH} High-level output voltage I _{OH} = -50μA 0.8DVDD V V _{OL} Low-level output voltage I _{OL} = 50μA 0.2DVDD V I _{Ikg} Input leakage current DGND < V _{DIGITAL INPUT} < DVDD | VREFP | | | 3.6 | 4.0 | 4.4 | V |
| DIGITAL INPUT/OUTPUT VI _{IH} High-level input voltage 0.7DVDD DVDD V VI _{IL} Low-level input voltage DGND 0.3DVDD V VI _{IL} Low-level input voltage I _{OH} = -50μA 0.8DVDD V VI _{IM} V V VI _{IM} V V VI _{IM} V V VI _{IM} V V VI _{IM} V V V V V V V V V | VREFN | | | 0.9 | 1.0 | 1.1 | V |
| V _{IH} High-level input voltage 0.7DVDD DVDD V V _{IL} Low-level input voltage DGND 0.3DVDD V V _{OH} High-level output voltage I _{OH} = -50μA 0.8DVDD V V _{OL} Low-level output voltage I _{OL} = 50μA 0.2DVDD V I _{Ikg} Input leakage current DGND < V _{DIGITAL INPUT} < DVDD | VMID | | | 2.2 | 2.5 | 3.8 | V |
| V _{IL} Low-level input voltage DGND 0.3DVDD V V _{OH} High-level output voltage I _{OH} = -50μA 0.8DVDD V V _{OL} Low-level output voltage I _{OL} = 50μA 0.2DVDD V I _{Ikg} Input leakage current DGND < V _{DIGITAL INPUT} < DVDD | DIGITAL | INPUT/OUTPUT | | | | | |
| VOH High-level output voltage I _{OH} = -50μA 0.8DVDD V VOL Low-level output voltage I _{OL} = 50μA 0.2DVDD V Il _{lkg} Input leakage current DGND < V _{DIGITAL INPUT} < DVDD | V_{IH} | | | | | | |
| Vol. Low-level output voltage I _{OL} = 50μA 0.2DVDD V Il _{kg} Input leakage current DGND < V _{DIGITAL INPUT} < DVDD | V_{IL} | | | | | 0.3DVDD | V |
| Input leakage current DGND < V _{DIGITAL INPUT} < DVDD ±10 μA | V_{OH} | | $I_{OH} = -50\mu A$ | 0.8DVDD | | | V |
| POWER-SUPPLY REQUIREMENTS | V_{OL} | Low-level output voltage | | | | 0.2DVDD | V |
| VAVDD AVDD voltage 4.9 5.0 5.1 V VDVDD DVDD voltage 2.7 3.0 3.6 V IAVDD AVDD current 150 170 mA IDVDD DVDD current 70 80 mA PD Power dissipation 960 1100 mW | I_{lkg} | | DGND < V _{DIGITAL INPUT} < DVDD | | | ±10 | μΑ |
| VDVDD DVDD voltage 2.7 3.0 3.6 V IAVDD AVDD current 150 170 mA IDVDD DVDD current 70 80 mA PD Power dissipation 960 1100 mW | | SUPPLY REQUIREMENTS | | T- | | | |
| AVDD current | V_{AVDD} | | | 4.9 | 5.0 | 5.1 | |
| DVDD current 70 80 mA | V_{DVDD} | DVDD voltage | | 2.7 | 3.0 | 3.6 | V |
| Po Power dissipation 960 1100 mW | I _{AVDD} | AVDD current | | | 150 | 170 | mA |
| Po Power dissipation mW | I_{DVDD} | DVDD current | | | 70 | 80 | mA |
| | P_D | Power dissipation | PD = low | | | 1100 | mW |

⁽¹⁾ There is a constant gain error of 3.8% in addition to the variable gain error of $\pm 0.3\%$. Therefore, the gain error is $3.8 \pm 0.3\%$.



DEVICE INFORMATION

PIN CONFIGURATION



TERMINAL FUNCTIONS

| | TERMINAL | ANALOG/DIGITAL | DESCRIPTION |
|-------|------------------------|---------------------------|--|
| NAME | NO. | INPUT/OUTPUT | DESCRIPTION |
| AGND | 1, 3, 6, 9, 11, 55 | Analog | Analog ground |
| AVDD | 2, 7, 10, 12 | Analog | Analog supply |
| AINN | 4 | Analog input | Negative analog input |
| AINP | 5 | Analog input | Positive analog input |
| RBIAS | 8 | Analog | Analog bias setting resistor |
| NC | 13, 16, 27, 28, 45–48 | _ | Must be left unconnected. |
| MODE | 14, 15 | Digital input | Control for four output modes (See MODE SELECTION section) |
| PD | 17 | Digital input; active low | Power-down |
| DVDD | 18, 26, 49, 50, 52, 53 | Digital | Digital supply |
| DGND | 19, 25, 51, 54 | Digital | Digital ground |
| SYNC | 20 | Digital input; active low | Digital reset |
| CS | 21 | Digital input; active low | Chip-select |



TERMINAL FUNCTIONS (continued)

| | TERMINAL | ANALOG/DIGITAL | DESCRIPTION |
|------------|----------|---------------------------|--|
| NAME | NO. | INPUT/OUTPUT | DESCRIPTION |
| RD | 22 | Digital input; Active low | Read enable |
| OTR | 23 | Digital output | Analog inputs out-of-range |
| DRDY | 24 | Digital output | Data ready |
| DOUT[15:0] | 29–44 | Digital output | Data output. DOUT[15] is the MSB and DOUT[0] is the LSB. |
| CLK | 56 | Digital input | Clock input |
| AGND2 | 57 | Analog | Analog ground for AVDD2 |
| AVDD2 | 58 | Analog | Analog supply for modulator clocking |
| VCAP | 59 | Analog | Bypass capacitor |
| VREFN | 60, 61 | Analog | Negative reference voltage |
| VMID | 62 | Analog | Midpoint voltage |
| VREFP | 63, 64 | Analog | Positive reference voltage |

TIMING SPECIFICATIONS

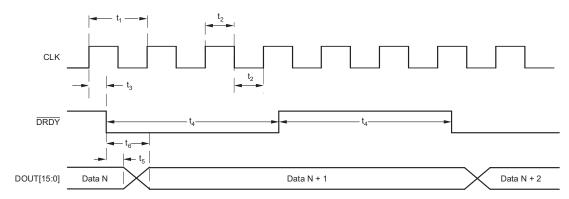


Figure 1. Data Retrieval Timing

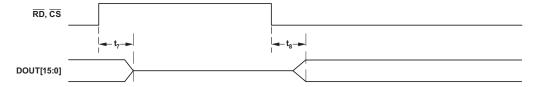


Figure 2. DOUT Inactive/Active Timing



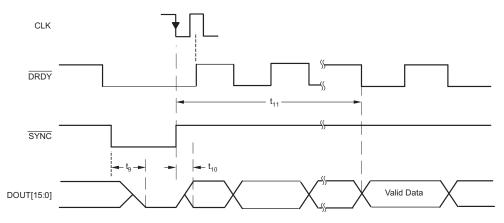


Figure 3. Reset Timing

Timing Specifications⁽¹⁾

| | DESCRIPTION | MIN | TYP | MAX | UNIT |
|------------------|---|--------|------------------|-----|------|
| t ₁ | CLK period (1/f _{CLK}) | 16.667 | | | ns |
| 1/t ₁ | f _{CLK} | 1 | | 60 | MHz |
| t_2 | CLK pulse width, high or low | 45% | | 55% | ns |
| t_3 | CLK to DRDY high (propagation delay) | | 12 | | ns |
| t ₄ | DRDY pulse width, high or low | | 3 t ₁ | | ns |
| t ₅ | Previous data valid (hold time) | 0 | | | ns |
| t ₆ | New data valid (setup time) | | | 5 | ns |
| t ₇ | RD and/or CS inactive (high) to DOUT high impedance | | 15 | | ns |
| t ₈ | RD and/or CS active (low) to DOUT active | | 15 | | ns |
| t ₉ | Delay from SYNC active (low) to all-zero DOUT[15:0] | | 12 | | ns |
| t ₁₀ | Delay from SYNC inactive (high) to non-zero DOUT[15:0] | | | 21 | DRDY |
| t ₁₁ | Delay from SYNC inactive (high)to valid DOUT[15:0] (time – 55 DRDY cycles; required for digital filter to settle). | | 55 | | DRDY |

⁽¹⁾ Output load = $10pF||500k\Omega$.



TYPICAL CHARACTERISTICS

At $T_A = 25$ °C, $R_{BIAS} = 19k\Omega$, AVDD = 5V, DVDD = 3V, $f_{CLK} = 60$ MHz, $V_{REF} = 3$ V, MODE = 00,and $V_{CM} = 2.5$ V (unless otherwise noted).

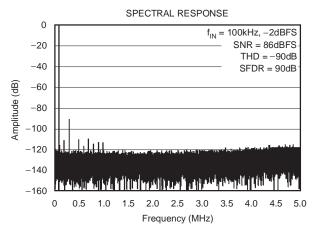


Figure 4.

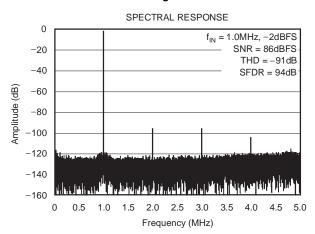


Figure 6.

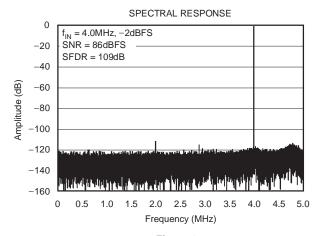


Figure 8.

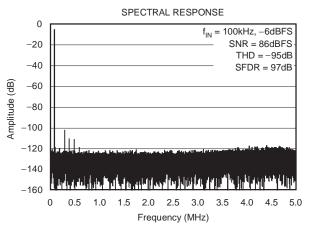


Figure 5.

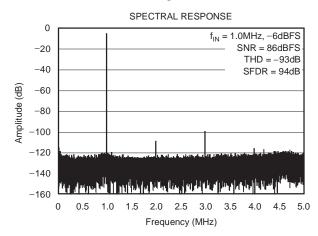


Figure 7.

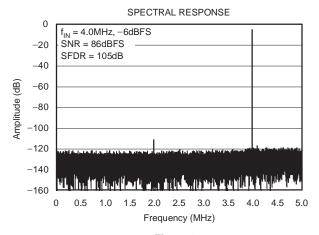


Figure 9.

SIGNAL-TO-NOISE RATIO vs INPUT FREQUENCY



TYPICAL CHARACTERISTICS (continued)

At $T_A = 25$ °C, $R_{BIAS} = 19k\Omega$, AVDD = 5V, DVDD = 3V, $f_{CLK} = 60$ MHz, $V_{REF} = 3$ V, MODE = 00,and $V_{CM} = 2.5$ V (unless otherwise noted).

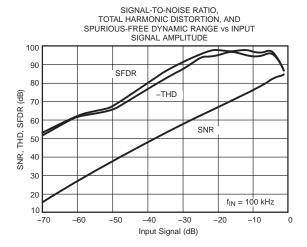


Figure 10.

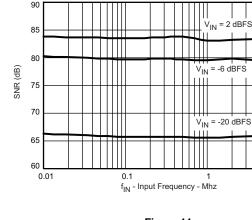


Figure 11.

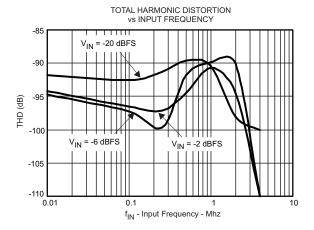


Figure 12.

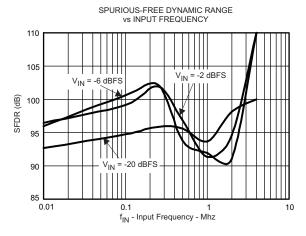


Figure 13.

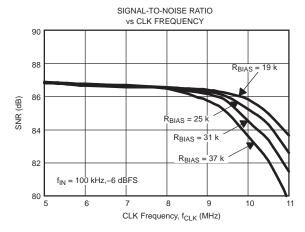


Figure 14.

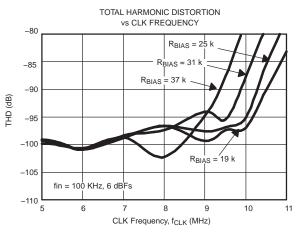


Figure 15.



TYPICAL CHARACTERISTICS (continued)

At T_A = 25°C, R_{BIAS} = 19k Ω , AVDD = 5V, DVDD = 3V, f_{CLK} = 60MHz, V_{REF} = 3V, MODE = 00,and V_{CM} = 2.5V (unless otherwise noted).

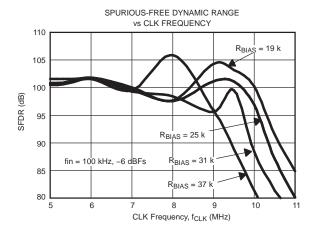


Figure 16.

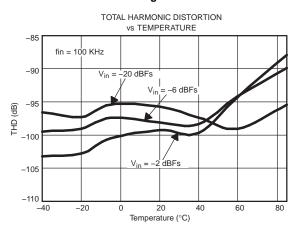


Figure 18.

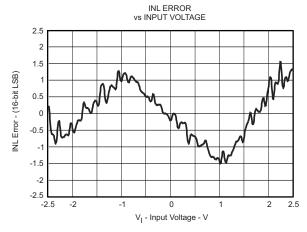


Figure 20.

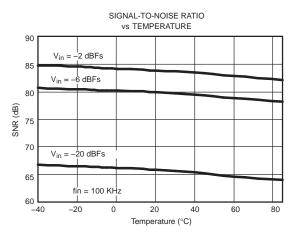


Figure 17.

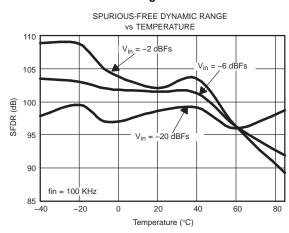


Figure 19.

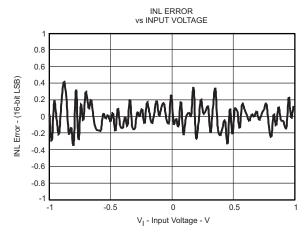
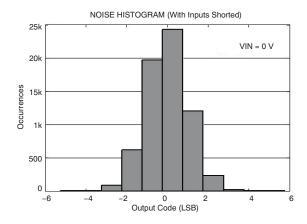


Figure 21.



TYPICAL CHARACTERISTICS (continued)

At T_A = 25°C, R_{BIAS} = 19k Ω , AVDD = 5V, DVDD = 3V, f_{CLK} = 60MHz, V_{REF} = 3V, MODE = 00,and V_{CM} = 2.5V (unless otherwise noted).





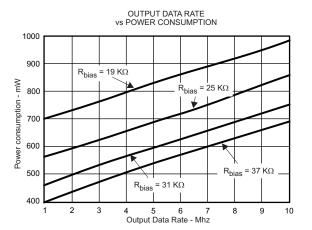


Figure 23.



OVERVIEW

The ADS1610 is a high-performance, delta-sigma ADC. The modulator uses an inherently stable, pipelined, delta-sigma modulator architecture incorporating proprietary circuitry that allows for very linear high-speed operation. The modulator samples the input signal at 60MSPS (when $f_{CLK}=60MHz$). A low-ripple linear phase digital filter decimates the modulator output by 6 to provide data output word rates of 10MSPS with a signal passband out to 4.9MHz.

Conceptually, the modulator and digital filter measure the differential input signal, $V_{ID} = (AINP - AINN)$, against the differential reference, $V_{ref} = (VREFP - VREFN)$, as shown in Figure 11. A 16-bit parallel data bus, designed for direct connection to DSPs, outputs the data. A separate power supply for the I/O allows flexibility for interfacing to different logic families. Out-of-range conditions are indicated with a dedicated digital output pin. Analog power dissipation is controlled using an external resistor. This allows reduced dissipation when operating at slower speeds. When not in use, power consumption can be dramatically reduced using the \overline{PD} pin.

ANALOG INPUTS (AINP, AINN)

The ADS1610 supports a very wide range of input signals. Having such a wide input range makes out-of-range signals unlikely. However, should an out-of-range signal occur, the digital output OTR will go high.

To achieve the highest analog performance, it is recommended that the inputs be limited to no greater than 0.891VREF (-1dBFS). For VREF = 3V, the corresponding recommended input range is 2.67V.

The analog inputs must be driven with a differential signal to achieve optimum performance. The recommended common-mode voltage of the input

recommended common-mode voltag signal,
$$V_{CM} = \frac{AINP + AINN}{2}$$
 is 2.5V.

In addition to the differential and common-mode input voltages, the absolute input voltage is also important. This is the voltage on either input (AINP or AINN) with respect to AGND. The range for this voltage is:

$$-0.1 \text{ V} < (AINN \text{ or AINP}) < 4.2 \text{ V}$$
 (1)

If either input is taken below -0.1V, ESD protection diodes on the inputs will turn on. Exceeding 4.2V on either input will result in linearity performance degradation. ESD protection diodes will also turn on if the inputs are taken above AVDD (+5V).

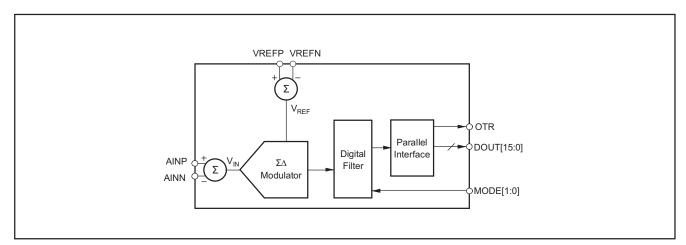


Figure 24. Conceptual Block Diagram

INPUT CIRCUITRY

The ADS1610 uses switched-capacitor circuitry to measure the input voltage. Internal capacitors are charged by the inputs and then discharged internally with this cycle repeating at the frequency of CLK. Figure 25 shows a conceptual diagram of these

circuits. Switches S_2 represent the net effect of the modulator circuitry in discharging the sampling capacitors, the actual implementation is different. The timing for switches S_1 and S_2 is shown in Figure 26.



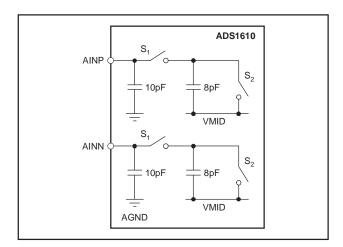


Figure 25. Conceptual Diagram of Internal Circuitry Connected to the Analog Inputs

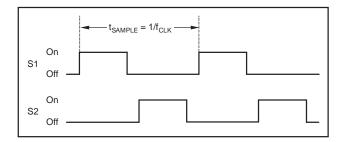


Figure 26. Timing for the Switches in Figure 25

DRIVING THE INPUTS

The external circuits driving the ADS1610 inputs must be able to handle the load presented by the switching capacitors within the ADS1610. The input switches S_1 in Figure 25 are closed approximately one half of the sampling period, t_{SAMPLE} , allowing only ~8 ns for the internal capacitors to be charged by the inputs, when $f_{CLK} = 60 MHz$.

Figure 27 and Figure 28 show the recommended circuits when using single-ended or differential op amps, respectively. The analog inputs must be driven differentially to achieve optimum performance. If only a single-ended input signal is available, the configuration in Figure 27 can be used by shorting $-V_{\text{IN}}$ to ground.

This configuration would implement the single-ended to differential conversion.

The external capacitors, between the inputs and from each input to AGND, improve linearity and should be placed as close to the pins as possible. Place the drivers close to the inputs and use good capacitor bypass techniques on their supplies; usually a smaller high-quality ceramic capacitor in parallel with a larger capacitor. Keep the resistances used in the

driver circuits low-thermal noise in the driver circuits degrades the overall noise performance. When the signal can be AC-coupled to the ADS1610 inputs, a simple RC filter can set the input common mode voltage. The ADS1610 is a high-speed, high-performance ADC. Special care must be taken when selecting the test equipment and setup used with this device. Pay particular attention to the signal sources to ensure they do not limit performance when measuring the ADS1610.

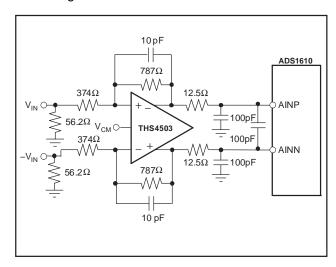


Figure 27. Recommended Single-Ended to Differential Conversion Circuit Using the THS4503 Differential Amplifier

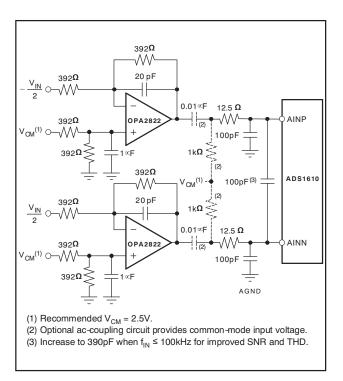


Figure 28. Recommended Driver Circuit Using the OPA2822



REFERENCE INPUTS (VREFN, VREFP, VMID)

The ADS1610 operates from an external voltage reference. The reference voltage (V_{ref}) is set by the differential voltage between VREFN and VREFP: V_{ref} = (VREFP – VREFN). VREFP and VREFN each use two pins, which should be shorted together. VMID, approximately 2.5V, is used by the modulator. VCAP connects to an internal node and must also be bypassed with an external capacitor.

The voltages applied to these pins must be within the values specified in the Electrical Characteristics table. Typically VREFP = 4V, VMID = 2.5V, and VREFN = 1V. The external circuitry must be capable of providing both a DC and a transient current. Figure 29 shows a simplified diagram of the internal circuitry of the reference. As with the input circuitry, switches S_1 and S_2 open and close as shown in Figure 26.

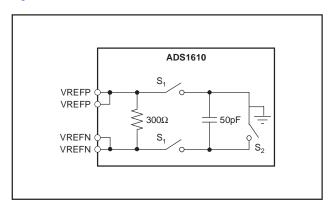


Figure 29. Conceptual Circuitry for the Reference Inputs

Figure 30 shows the recommended circuitry for driving these reference inputs. Keep the resistances used in the buffer circuits low to prevent excessive thermal noise from degrading performance. Layout of these circuits is critical, make sure to follow good high-speed layout practices. Place the buffers and especially the bypass capacitors as close to the pins as possible.

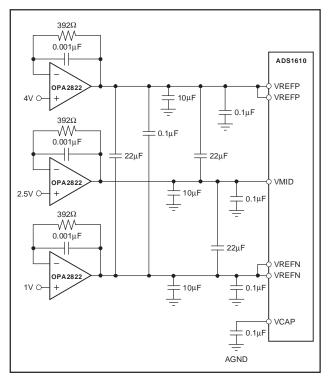


Figure 30. Recommended Reference Buffer Circuit

CLOCK INPUT (CLK)

The ADS1610 uses an external clock signal to be applied to the CLK input pin. The sampling of the modulator is controlled by this clock signal. As with any high-speed data converter, a high quality clock is essential for optimum performance. Crystal clock oscillators are the recommended CLK source; other sources, such as frequency synthesizers may not be adequate. Make sure to avoid excess ringing on the CLK input; keeping the trace as short as possible will help.

Measuring high-frequency, large-amplitude signals requires tight control of clock jitter. The uncertainty during sampling of the input from clock jitter limits the maximum achievable SNR. This effect becomes more pronounced with higher frequency and larger magnitude inputs. The ADS1610 oversampling topology reduces clock jitter sensitivity over that of Nyquist rate converters like pipeline and successive approximation converters by a factor of $\sqrt{6}$.

In order to not limit the ADS1610 SNR performance, keep the jitter on the clock source below the values shown in Table 1. When measuring lower frequency and lower amplitude inputs, more CLK jitter can be tolerated. In determining the allowable clock source jitter, select the worst-case input (highest frequency, largest amplitude) that will be seen in the application.



DATA FORMAT

The 16-bit output data is in binary two's complement format, as shown in Table 2. When the input is positive out-of-range, exceeding the positive full-scale value of V_{REF} , the output clips to all 7FFF_H and the OTR output goes high.

Table 1. Maximum Allowable Clock Source Jitter for Different Input Signal Frequencies and Amplitude

| INPUT | INPUT SIGNAL | | | | |
|----------------------|----------------------|-------------------------------------|--|--|--|
| MAXIMUM FREQUENCY | MAXIMUM AMPLITUDE | ALLOWABLE CLOCK SOURCE JITTER | | | |
| 4MHz | -1dB | 1.6ps | | | |
| 4MHz | -20dB | 14ps | | | |
| 2MHz | -1dB | 3.3ps | | | |
| 2MHz | -20dB | 29ps | | | |
| 1MHz | −1dB | 6.5ps | | | |
| 1MHz | -20dB | 58ps | | | |
| 100kHz | -1dB | 65ps | | | |
| 100kHz | -20dB | 581ps | | | |

Table 2. Output Code Versus Input Signal

| INPUT SIGNAL (INP – INN) | IDEAL OUTPUT CODE ⁽¹⁾ | OTR | | | | |
|--|-------------------------------------|--------------|--|--|--|--|
| ≥ +V _{ref} (> 0dB) | 7FFF _H | 1 | | | | |
| V _{ref} (0dB) | 7FFF _H | 0 | | | | |
| + V _{REF} 2 ¹⁵ – 1 | 0001 _H | 0 | | | | |
| 0 | 0000 _H | 0 | | | | |
| -V _{REF} 2 ¹⁵ - 1 | FFFF _H | 0 | | | | |
| $-V_{REF}\left(\frac{2^{15}}{2^{15}-1}\right)$ 8000 _H 0 | | | | | | |
| $\leq -V_{REF} \left(\frac{2^{15}}{2^{15} - 1} \right)$ 8000 _H 1 | | | | | | |
| (1)Excludes effects of | noise, INL, offset and | gain errors. | | | | |

Likewise, when the input is negative out-of-range by going below the negative full-scale value of V_{ref} , the output clips to 8000_{H} and the OTR output goes high. The OTR remains high while the input signal is out-of-range.

OUT-OF-RANGE INDICATION (OTR)

If the output code on DOUT[15:0] exceeds the positive or negative full-scale, the out-of-range digital output (OTR) will go high on the falling edge of DRDY. When the output code returns within the full-scale range, OTR returns low on the falling edge of DRDY.

DATA RETRIEVAL

Data retrieval is controlled through a simple parallel interface. The falling edge of the \overline{DRDY} output indicates new data is available. To activate the output bus, both \overline{CS} and \overline{RD} must be low, as shown in Table 3. Make sure the DOUT bus does not drive heavy loads (> 20pF), as this will degrade performance. Use an external buffer when driving an edge connector or cables.

Table 3. Truth Table for CS and RD

| CS | RD | DOUT [15:0] |
|---------------|----|----------------|
| 0 | 0 | Active |
| 0 | 1 | High impedance |
| 1 | 0 | High impedance |
| 1 | 1 | High impedance |

SYNCHRONISING MULTIPLE ADS1610s

The ADS1610 is asynchronously reset when the SYNC pin is taken low. During reset, all of the digital circuits are cleared, DOUT[15:0] are forced low, and DRDY forced high. It is recommended that the SYNC pin be released on the falling edge of CLK. Afterwards, DRDY goes low on the second rising edge of CLK. Allow 55 DRDY cycles for the digital filter to settle before retrieving data. See Figure 3 for the timing specifications.

Reset can be used to synchronize multiple ADS1610s. All devices to be synchronized must use a common CLK input. With the CLK inputs running, pulse $\overline{\text{SYNC}}$ on the falling edge of CLK, as shown in Figure 31. Afterwards, the converters will be converting synchronously with the $\overline{\text{DRDY}}$ outputs updating simultaneously. After synchronization, allow $\overline{\text{DRDY}}$ cycles (t_{11}) for output data to fully settle.



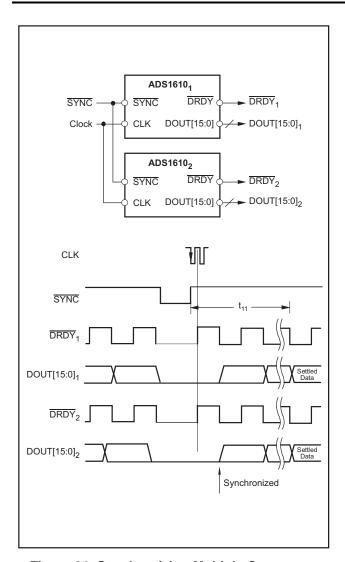


Figure 31. Synchronizing Multiple Converters

SETTLING TIME

The settling time is an important consideration when measuring signals with large steps or when using a multiplexer in front of the analog inputs. The ADS1610 digital filter requires time for an instantaneous change in signal level to propagate to the output.

Be sure to allow the filter time to settle after applying a large step in the input signal, switching the channel on a multiplexer placed in front of the inputs, resetting the ADS1610, or exiting the power-down mode.

Figure 32 shows the settling error as a function of time for a full-scale signal step applied at t=0, with MODE = 00 (See Table 4). This figure uses \overline{DRDY} cycles for the ADS1610 for the time scale (X-axis). After 55 \overline{DRDY} cycles, the settling error drops below 0.001%. For $f_{CLK}=60MHz$, this corresponds to a settling time of 5.5 μ s.

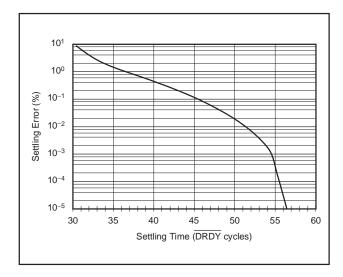


Figure 32. Settling Time

IMPULSE RESPONSE

Figure 33 plots the normalized response for an input applied at t=0, with MODE = 00. The X-axis units of time are \overline{DRDY} cycles for the ADS1610. As shown in Figure 33, the peak of the impulse takes 30 \overline{DRDY} cycles to propagate to the output. For $f_{CLK}=60$ MHz, a \overline{DRDY} cycle is 0.1 μ s in duration and the propagation time (or group delay) is 30 × 0.1 μ s = 3.0 μ s.

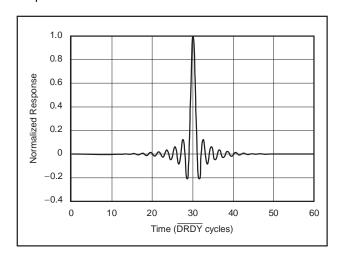


Figure 33. Impulse Response



FREQUENCY RESPONSE

The linear phase FIR digital filter sets the overall frequency response. The decimation rate is set to 6 (MODE = 00) for all the figures shown in this section. Figure 34 shows the frequency response from DC to 30 MHz for $f_{CLK} = 60$ MHz. The frequency response of the ADS1610 filter scales directly with CLK frequency. For example, if the CLK frequency is decreased by half (to 30 MHz), the values on the X-axis in Figure 34 would need to be scaled by half, with the span becoming DC to 15MHz.

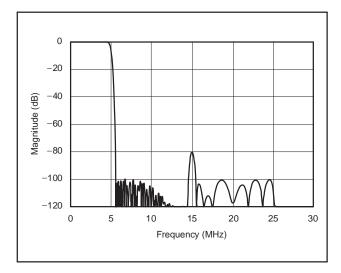


Figure 34. Frequency Response

Figure 35 shows the passband ripple from DC to 4.4MHz ($f_{CLK} = 60MHz$). Figure 36 shows a closer view of the passband transition by plotting the response from 4.0MHz to 5.0MHz ($f_{CLK} = 60MHz$).

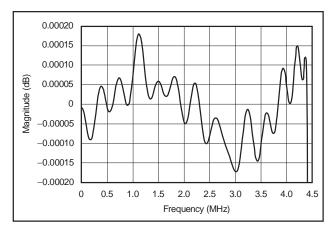


Figure 35. Passband Ripple

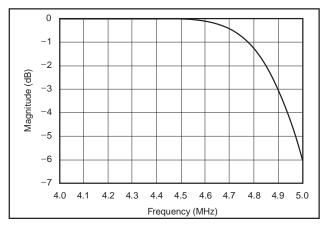


Figure 36. Passband Transition

The overall frequency response repeats at multiples of the CLK frequency. To help illustrate this, Figure 37 shows the response out to 180 MHz ($f_{\rm CLK} = 60 \rm MHz$). Notice how the passband response repeats at 60 MHz, 120 MHz, and 180 MHz; it is important to consider this sequence when there is high-frequency noise present with the signal. The modulator bandwidth extends to 100 MHz. High-frequency noise around 60 MHz and 120 MHz will not be attenuated by either the modulator or the digital filter. This noise will alias back inband and reduce the overall SNR performance unless it is filtered out prior to the ADS1610. To prevent this, place an anti-alias filter in front of the ADS1610 that rolls off before 55 MHz.

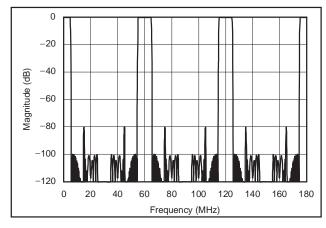


Figure 37. Frequency Response Out to 120MHz



NOISE FLOOR

The ADS1610 is a delta sigma ADC and it uses noise shaping to achieve superior SNR performance. The noise floor of a typical successive approximation (SAR) or a pipeline ADC remains flat until the nyquist frequency occurs. A gain of 3dB in SNR can be achieved by averaging two samples, thereby having a tradeoff between output data rate and achievable SNR. In contrast, the noise floor of the ADS1610 inside the bandwidth of interest is shaped. Hence, the gain in SNR that can be achieved by averaging

two samples is more than 3dB. Figure 38 below shows the typical in-band noise spectral density of the ADS1610. The numbers in the bottom of the figure represent the noise distribution with respect to a full-scale signal in different bandwidths of interest. The shaded area represents the signal bandwidth in the default mode of operation (10MHz output data rate).

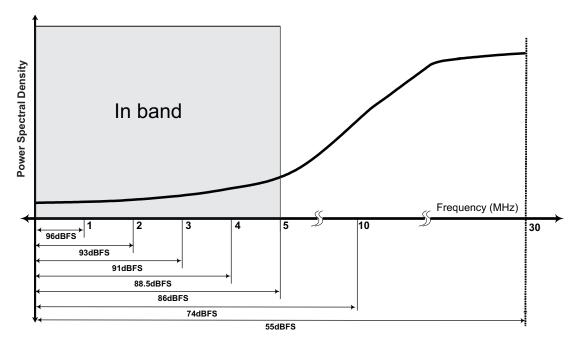


Figure 38. Typical Filter Bypass Mode Noise Spectral Density

By using appropriate filtering the user can achieve a tradeoff between speed and SNR. For ease of use, the ADS1610 provides four filtering modes as explained in the next section. Figure 39 shows a conceptual diagram of the available filtering modes. Custom filtering is achieved by taking the modulator output data and adding a filter externally.

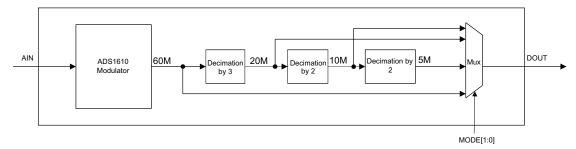


Figure 39. Conceptual Diagram of the ADS1610 Filtering Modes

MODE SELECTION

ADS1610 offers four different modes of operation each with different output data rates. This gives users the flexibility to choose the best output rate for their application. The outputs of all modes are MSB-aligned.



| Mode 1 | Mode 0 | OUTPUT RATE | OSR | SNR (TYP) | BITS | SETTLING TIME (DRDY cycles) |
|--------|--------|--------------------|-----|-----------|------|-----------------------------|
| 0 | 0 | Default 10MHz mode | 6 | 86dBFS | 16 | 55 |
| 0 | 1 | 20MHz | 3 | 74dBFS | 14 | 25 |
| 1 | 0 | 5MHz | 12 | 91dBFS | 16 | 55 |
| 1 | 1 | 60MHz bypass mode | 1 | 55dBFS | 12 | NA |

Table 4. Four Modes of Operation⁽¹⁾

(1) There is a pull-down resistor of $170k\Omega$ on both mode pins; however, it is recommended that this pin be reduced to either high or low.

20MHz MODE

In this mode, the oversampling ratio is three. Decreasing the OSR from 6 to 3 doubles the data rate, at the same time the performance is reduced from 16 bits to 14 bits. Note that all 16 bits of DOUT remain active in this mode. For $f_{\text{clk}}=60\text{MHz},$ the data rate is 20MSPS. In addition, the group delay becomes 1 μs or 13 $\overline{\text{DRDY}}$ cycles. In this mode the noise increases. Typical SNR performance degrades by 14dB. THD remains approximately the same.

5MHz MODE

In this mode the OSR is 12 for $f_{clk}=60 MHz$ and the data rate in 5MSPS. Typical SNR performance increases by 4dB. THD remains approximately the same.

60MHz MODE

In this mode, decimation filters are bypassed. This data output can be filtered externally by the user. For $f_{\text{clk}} = 60\text{MHz}$, the data rate is 60MSPS.

ANALOG POWER DISSIPATION

An external resistor connected between the RBIAS pin and the analog ground sets the analog current level, as shown in Figure 40. The current is inversely proportional to the resistor value. Table 5 shows the recommended values of RBIAS for different CLK frequencies. Notice that the analog current can be reduced when using a slower frequency CLK input because the modulator has more time to settle. Avoid adding any capacitance in parallel to RBIAS, since this will interfere with the internal circuitry used to set the biasing.

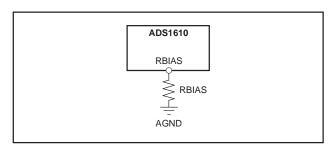


Figure 40. External Resistor Used to Set Analog Power Dissipation

Table 5. Recommended RBIAS Resistor Values for Different CLK Frequencies

| f _{CLK} | DATA RATE | RBIAS | TYPICAL POWER DISSIPATION |
|------------------|--------------|-------|---------------------------|
| 42MHz | 7MHz | 45kΩ | 550mW |
| 48MHz | 8MHz | 37kΩ | 640mW |
| 54MHz | 9MHz | 31kΩ | 720mW |
| 60MHz | 10MHz | 19kΩ | 960mW |

POWER-DOWN (PD)

When not in use, the ADS1610 can be powered down by taking the \overline{PD} pin low. There is an internal pull-up resistor of $170k\Omega$ on the \overline{PD} pin, but it is recommended that this pin be connected to DVDD if not used. Once the \overline{PD} pin is pulled high, allow at least t_{11} (see Timing Specification Table) \overline{DRDY} cycles for the modulator and the digital filter to settle before retrieving data.

POWER SUPPLIES

Two supplies are used on the ADS1610: analog (AVDD), and digital (DVDD). Each supply (other than DVDD pins 49 and 50) must be suitably bypassed to achieve the best performance. It is recommended that a $1\mu F$ and $0.1\mu F$ ceramic capacitor be placed as close to each supply pin as possible. Connect each supply-pin bypass capacitor to the associated ground, as shown in Figure 41. Each main supply bus should also be bypassed with a bank of capacitors from $47\mu F$ to $0.1\mu F$, as shown in Figure 41.

For optimum performance, insert a 10Ω resistor in series with the AVDD2 supply (pin 58); the modulator clocking circuitry. This resistor decouples switching.



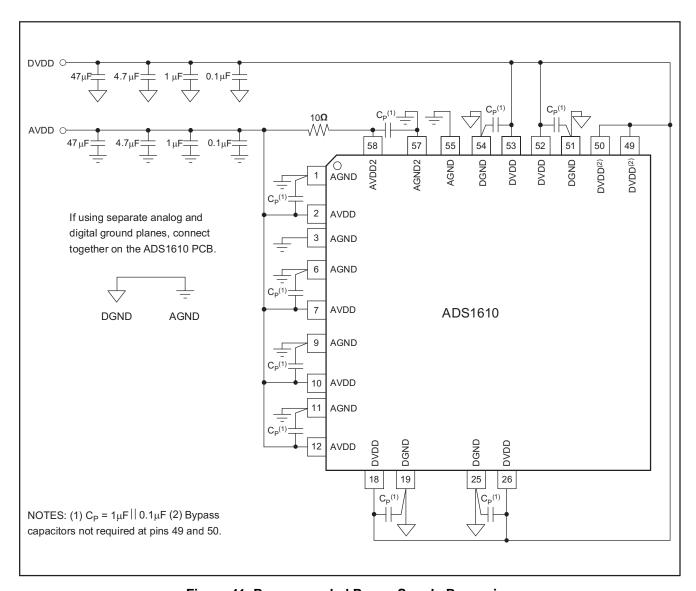


Figure 41. Recommended Power-Supply Bypassing

LAYOUT ISSUES

The ADS1610 is a very high-speed, high-resolution data converter. In order to achieve the maximum performance, careful attention must be given to the printed circuit board (PCB) layout. Use good high-speed techniques for all circuitry. Critical capacitors should be placed close to pins as possible. These include capacitors directly connected to the analog and reference inputs and the power supplies. Make sure to also properly bypass all circuitry driving the inputs and references.

Two approaches can be used for the ground planes: either a single common plane; or two separate

planes, one for the analog grounds and one for the digital grounds. When using only one common plane, isolate the flow of current on AGND2 (pin 57) from pin 1; use breaks on the ground plane to accomplish this. AGND2 carries the switching current from the analog clocking for the modulator and can corrupt the quiet analog ground on pin 1. When using two planes, it is recommended that they be tied together right at the PCB. Do not try to connect the ground planes together after running separately through edge connectors or cables as this reduces performance and increases the likelihood of latch-up.



In general, keep the resistances used in the driving circuits for the inputs and reference low to prevent excess thermal noise from degrading overall performance. Avoid having the ADS1610 digital outputs drive heavy loads. Buffers on the outputs are recommended unless the ADS1610 is connected directly to a DSP or controller situated nearby. Additionally, make sure the digital inputs are driven with clean signals as ringing on the inputs can introduce noise.

The ADS1610 uses TI PowerPAD™ technology. The PowerPAD is physically connected to the substrate of the silicon inside the package and must be soldered to the analog ground plane on the PCB using the exposed metal pad underneath the package for proper heat dissipation. See application report SLMA002, located at www.ti.com, for more details on the PowerPAD package.

APPLICATION INFORMATION

INTERFACING THE ADS1610 TO THE TMS320C6000

Figure 42 illustrates how to directly connect the ADS1610 to the TMS320C6000 DSP. The processor controls reading using output ARE. The ADS1610 is selected using the DSP control output, CE2. The ADS1610 16-bit data output bus is directly connected to the TMS320C6000 data bus. The data ready output (DRDY) from the ADS1610 drives interrupt EXT_INT7 on the TMS320C6000.

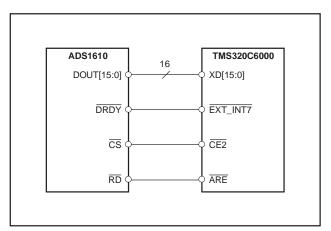


Figure 42. ADS1610 – TMS320C6000 Interface Connection

INTERFACING THE ADS1610 TO THE TMS320C5400

Figure 43 illustrates how to connect the ADS1610 to the TMS320C5400 DSP. The processor controls the reading using the outputs R/\overline{W} and \overline{IS} . The I/O space-select signal (\overline{IS}) is optional and is used to prevent the ADS1610 \overline{RD} input from being strobed when the DSP is accessing other external memory

spaces (address or data). This can help reduce the possibility of digital noise coupling into the ADS1610. When not using this signal, replace NAND gate U1 with an inverter between R/W and RD. Two signals, $\overline{\text{IOSTRB}}$ and A15, combine using NAND gate U2 to select the ADS1610. If there are no additional devices connected to the TMS320C5400 I/O space, U2 can be eliminated. Simply connect $\overline{\text{IOSTRB}}$ directly to $\overline{\text{CS}}$. The ADS1610 16-bit data output bus is directly connected to the TMS320C5400 data bus. The data ready output ($\overline{\text{DRDY}}$) from the ADS1610 drives interrupt $\overline{\text{INT3}}$ on the TMS320C5400.

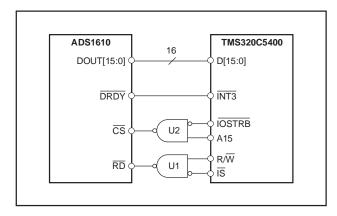


Figure 43. ADS1610 – TMS320C5400 Interface Connection

Code Composer Studio, available from TI, provides support for interfacing TI DSPs through a collection of data converter plug-ins. Check the TI website, located at www.ti.com/sc/dcplug-in, for the latest information on ADS1610 support.

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PACKAGING INFORMATION

| Orderable part number | Status | Material type | Package Pins | Package qty Carrier | RoHS | Lead finish/ | MSL rating/ | Op temp (°C) | Part marking |
|-----------------------|--------|---------------|------------------|-----------------------|------|---------------|---------------------|--------------|--------------|
| | (1) | (2) | | | (3) | Ball material | Peak reflow | | (6) |
| | | | | | | (4) | (5) | | |
| ADS1610IPAPR | NRND | Production | HTQFP (PAP) 64 | 1000 LARGE T&R | Yes | NIPDAU | Level-3-260C-168 HR | -40 to 85 | ADS1610I |
| ADS1610IPAPR.B | NRND | Production | HTQFP (PAP) 64 | 1000 LARGE T&R | Yes | NIPDAU | Level-3-260C-168 HR | -40 to 85 | ADS1610I |
| ADS1610IPAPT | NRND | Production | HTQFP (PAP) 64 | 250 SMALL T&R | Yes | NIPDAU | Level-3-260C-168 HR | -40 to 85 | ADS1610I |
| ADS1610IPAPT.B | NRND | Production | HTQFP (PAP) 64 | 250 SMALL T&R | Yes | NIPDAU | Level-3-260C-168 HR | -40 to 85 | ADS1610I |

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





| A0 | Dimension designed to accommodate the component width |
|----|---|
| В0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|-----------------|--------------------|----|------|--------------------------|--------------------------|------------|------------|------------|------------|-----------|------------------|
| ADS1610IPAPR | HTQFP | PAP | 64 | 1000 | 330.0 | 24.4 | 13.0 | 13.0 | 1.5 | 16.0 | 24.0 | Q2 |
| ADS1610IPAPT | HTQFP | PAP | 64 | 250 | 180.0 | 24.4 | 13.0 | 13.0 | 1.5 | 16.0 | 24.0 | Q2 |



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*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| ADS1610IPAPR | HTQFP | PAP | 64 | 1000 | 350.0 | 350.0 | 43.0 |
| ADS1610IPAPT | HTQFP | PAP | 64 | 250 | 213.0 | 191.0 | 55.0 |

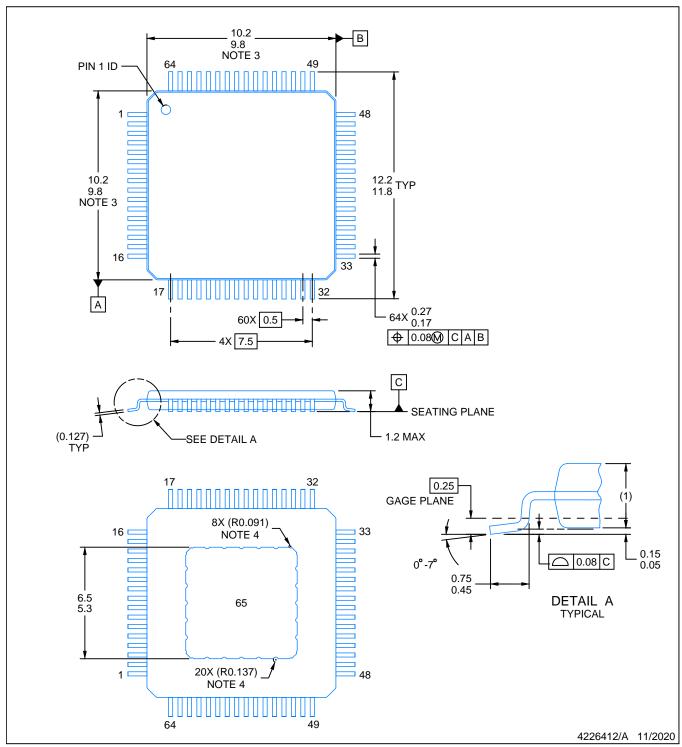
10 x 10, 0.5 mm pitch

QUAD FLATPACK

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



PLASTIC QUAD FLATPACK



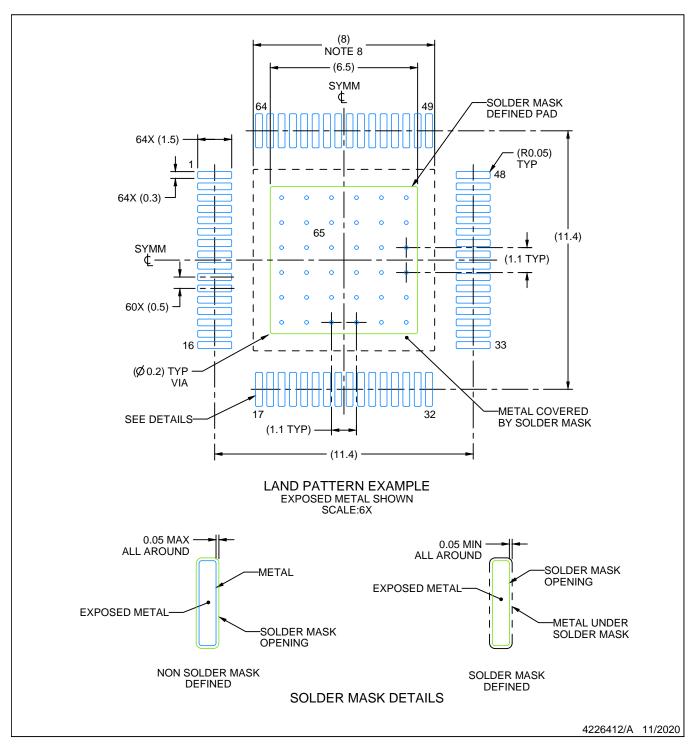
NOTES:

PowerPAD is a trademark of Texas Instruments.

- All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs.
- 4. Strap features may not be present.
- 5. Reference JEDEC registration MS-026.



PLASTIC QUAD FLATPACK

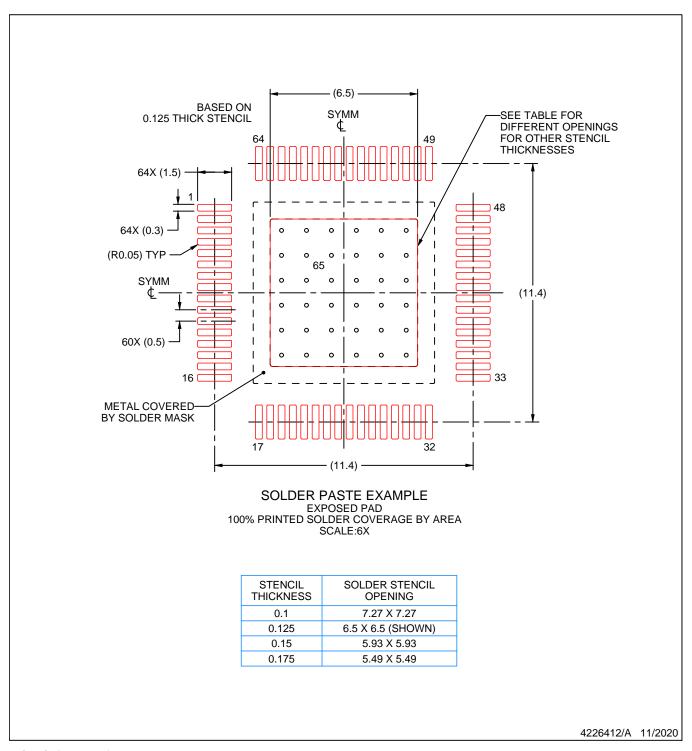


NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
- 8. This package is designed to be soldered to a thermal pad on the board. See technical brief, Powerpad thermally enhanced package, Texas Instruments Literature No. SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
- 9. Vias are optional depending on application, refer to device data sheet. It is recommended that vias under paste be filled, plugged or tented.
- 10. Size of metal pad may vary due to creepage requirement.



PLASTIC QUAD FLATPACK



NOTES: (continued)

- 11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 12. Board assembly site may have different recommendations for stencil design.



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